BOMcheck.net

Full Material Declaration for attached parts list

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Declarations authorised by
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2007 [Approved on 11 October 2018, 11:17 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	2.00000%	Nickel REACH Article 67 Exemption	8049-31-8	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethylsiloxane rubber	63394-02-5	25.00000%
			Silicon	7440-21-3	62.50000%
Die attach	Lead and Lead alloys	1.20000%	SILVER METAL	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements	7439-92-1	92.50000%
Encapsulation	Other thermoplastics	40.00000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE Exempt from industry substance restrictions	1309-64-4	0.80000%
			3,5,3â¬5âTetrabromo-bisphenol A (TBBA)	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz silica	14808-60-7	70.30000%
Leadfinish	Tin plating	0.50000%	Tin	7440-31-5	100.00000%
Leadframe	Copper alloys	56.30000%	Copper	7440-50-8	100.00000%

Attached parts list

Part number	Part name
GBUxxX	Bridge Rectifier Single Inline

Based on the information currently available, these substances do not pose any risk if the articles are used as intended (including disposal). Additional information is not necessary to allow safe use of the article.